SMD Power Inductor

TMPC0302H-Serise(G)

| | | ECN HISTO | RY LIS | Т | |
|-----|----------|-------------|----------|---------|-------|
| REV | DATE | DESCRIPTION | APPROVED | CHECKED | DRAWN |
| 1.0 | 14/05/19 | 新發行 | 楊祥忠 | 詹偉特 | 徐允珮 |
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SMD Power Inductor

TMPC0302H-Serise(G)

1. Features

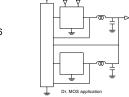
- 1. Carbonyl Powder.
- 2. Compact design.
- 3. High current , low DCR , high efficiency.
- 4. Very low acoustic noise and very low leakage flux noise.
- 5. High reliability.
- 6. 100% Lead(Pb)-Free and RoHS compliant.



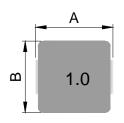


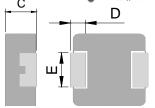
2. Applications

Note PC power system $\,^{,}$ incl. IMVP-6 DC/DC converter .



3. Dimensions

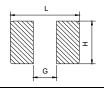






| Series | A(mm) | B(mm) | C(mm) | D(mm) | E(mm) |
|-----------|---------|---------|---------|---------|---------|
| TMPC0302H | 3.5±0.2 | 3.2±0.2 | 1.8±0.2 | 0.7±0.2 | 1.2±0.2 |

Recommend PC Board Pattern



| L(mm) | G(mm) | H(mm) |
|-------|-------|-------|
| 4.1 | 1.9 | 1.45 |

4. Part Numbering



A: Series

B: Dimension C: Type BxC Carbonyl Powder.

D: Inductance

1R0=1.00uH

E: Inductance Tolerance M=±20%,Y=±30%, 印字:黑色,單向印字,1.0 中間打點.

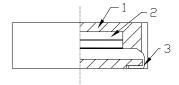
5. Specification

| Part Number | Inductance L0 (uH)±20% @ 0 A | I rms (A) Typ. | I sat (A) Typ. | DCR(mΩ) Typ.@25℃ | DCR(mΩ) Max.@25℃ |
|-----------------|---------------------------------|-------------------|-------------------|---------------------|---------------------|
| TMPC0302H-R47MG | 0.47 | 7.0 | 9.0 | 19.7 | 23 |
| TMPC0302H-R68MG | 0.68 | 5.5 | 7.0 | 25.5 | 29 |
| TMPC0302H-1R0MG | 1.00 | 4.0 | 5.0 | 32 | 38 |
| TMPC0302H-1R5MG | 1.50 | 3.8 | 4.0 | 42 | 50 |
| TMPC0302H-2R2MG | 2.20 | 3.5 | 3.7 | 65 | 75 |
| TMPC0302H-3R3MG | 3.30 | 3.0 | 3.5 | 125 | 145 |
| TMPC0302H-4R7MG | 4.70 | 2.6 | 3.0 | 172 | 200 |
| TMPC0302H-5R6MG | 5.60 | 2.2 | 2.6 | 205 | 238 |
| TMPC0302H-6R8MG | 6.80 | 1.9 | 2.2 | 260 | 300 |
| TMPC0302H-8R2MG | 8.20 | 1.6 | 1.9 | 340 | 390 |
| TMPC0302H-100MG | 10.0 | 1.4 | 1.6 | 366 | 422 |

Note:

- 1. Test frequency: L: 100KHz /1.0V.
- 2. All test data referenced to 25°C ambient.
- $3. \ \ \mathsf{Testing\ Instrument: L/Q: HP4284A, CH11025, CH3302, CH1320S\ LCR\ METER\ /\ Rdc: CH16502, Agilent 33420A\ MICRO\ OHMMETER.}$
- 4. Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C (keep 1min.).
- 5. Saturation Current (Isat) will cause L0 to drop 30% typical. (keep quickly).
- 6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
- 7. Special inquiries besides the above common used types can be met on your requirement.

6. Material List



| NO | Items | Materials |
|----|----------------|-------------------------------|
| 1 | Core | Carbonyl Powder. |
| 2 | Wire | Polyester Wire or equivalent. |
| 3 | Solder Plating | 100% Pb free solder |

7. Reliability and Test Condition

| Item | Performance | Test Condition |
|--|--|---|
| Operating temperature | -40~+125℃ | |
| Storage temperature and Humidity range | -40~+125°C (For products in unopened tape package, less than 40°C) 50~60%RH (Product without taping) | |
| Electrical Performance Tes | st | |
| Inductance | Refer to standard electrical characteristics list. | HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter. |
| DCR | | CH16502,Agilent33420A Micro-Ohm Meter. |
| Saturation Current (Isat) | △L30% typical. | Saturation DC Current (Isat) will cause L0 to drop $\triangle L(\%)$ (keep quickly). |
| Heat Rated Current (Irms) | Approximately △T≦40°C | Heat Rated Current (Irms) will cause the coil temperature rise △T(°C) without core loss. 1. Applied the allowed DC current(keep 1 min.). 2. Temperature measured by digital surface thermometer |
| Reliability Test | | |
| High Temperature Exposure Test | | Temperature:125±2°C. Duration:500±8hrs. Measured at room temperature after placing for 2 to 3hrs. (MIL-STD-202 Method 108) |
| Low Temperature Life Test | | Temperature:-40±2℃. Duration:500±8hrs. Measured at room temperature after placing for 2 to 3hrs. (JESD22-A119) |
| Biased Humidity Test | | Humidity:90-95%. Temperature:40±2°C. Duration:500±8hrs. Measured at room temperature after placing for 2 to 3hrs (AEC-Q200-REV C) |
| Thermal shock test | Electric specifications should be satisfied | Condition for 1 cycle $ \begin{array}{ll} \text{Step 1:} 40+0 \ / - 2^{\circ} \mathbb{C} & 15\pm 1 \text{ min.} \\ \text{Step 2:} \text{Room temperature within } \leq 0.2 \text{ min.} \\ \text{Step 3:} +125+2 \ / -0^{\circ} \mathbb{C} & 15\pm 1 \text{min.} \\ \text{Number of cycles:} 300 \\ \text{Measured at room temperature after placing for 2 to 3 hrs.} \\ \text{(AEC-Q200)} \end{array} $ |
| Vibration test | | Frequency: 10-2000-10Hz for 20 min. Amplitude: Parts mounted within 2" from any secure point. Directions and times: X, Y, Z directions for 20 min. This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 12hours). (MIL-STD-202 Method 204 D Test condition B) |
| Reflow test | | Pre-heat : 150±5°C Duration : 5 minutes Temperature : 260±5°C → 20~40 seconds (IPC/JEDEC J-STD-020C) |
| Solder test | Terminals should be covered by over 95% solder on visual inspection | After dip into flux · dip into solder 235±5°C · 4±1seconds Flux · solder for lead free (ANSI /J-STD-002C Method B) |

8. Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. TAIPAQ terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

(2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

(3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm

- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- · Limit soldering time to 4~5sec.

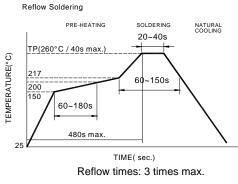
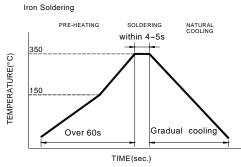


Fig.1

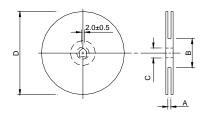


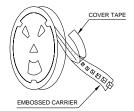
Iron Soldering times: 1 times max.

Fig.2

9. Packaging Information

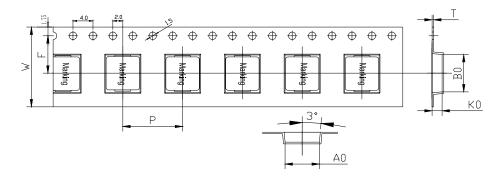
(1) Reel Dimension





| Туре | A(mm) | B(mm) | C(mm) | D(mm) |
|----------|----------|-------|----------|-------|
| 13"x12mm | 12.0±0.5 | 100±2 | 13.5±0.5 | 330 |

(2) Tape Dimension

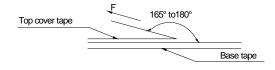


| Series | Size | Bo(mm) | Ao(mm) | Ko(mm) | P(mm) | W(mm) | F(mm) | t(mm) |
|--------|------|---------|---------|---------|---------|--------|---------|-----------|
| TMPC | 0302 | 3.9±0.1 | 3.6±0.1 | 2.3±0.1 | 8.0±0.1 | 12±0.3 | 5.5±0.1 | 0.35±0.05 |

(3) Packaging Quantity

| ТМРС | 0302 |
|-------------|-------|
| Chip / Reel | 3000 |
| Inner box | 6000 |
| Carton | 24000 |

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 stadnard).

| Room Temp. | Room Humidity | Room atm | Tearing Speed mm/min |
|------------|---------------|----------|----------------------|
| (℃) | (%) | (hPa) | |
| 5~35 | 45~85 | 860~1060 | 300 |

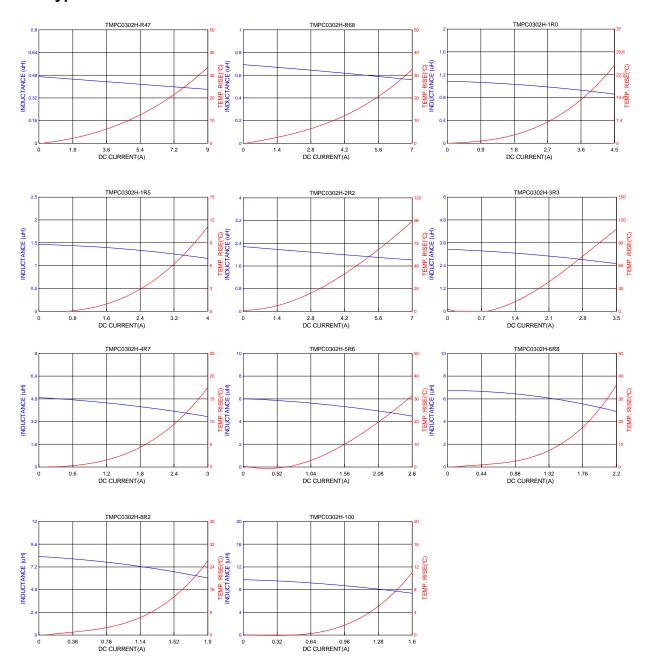
Application Notice

Storage Conditions

- To maintain the solderability of terminal electrodes:

 1. TAIPAQ products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

10. Typical Performance Curves





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Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

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(廣東省東莞市黄江鎮黄牛埔福祥街2號 / NO. 2, FUXIANG STREET, HUANGNIUPU, HUANGJIANG TOWN, DONGGUAN, GUANGDONG)

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(桃園縣中壢市中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN (R. O. C.))

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

: SMD POWER INDUCTOR

樣品型號(Style/Item No.)

: TMPB, TMPC, SLPI, SMPI, SMPI-P3, EPI(ePI), VMPI, MLPI SERIES

收件日期(Sample Receiving Date)

: 2014/01/20

測試期間(Testing Period)

: 2014/01/20 TO 2014/01/24

測試結果(Test Results) : 請見下一頁 (Please refer to next pages).



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測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

| 測試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限値 (MDL) | 結果 (Result) No.1 |
|-------------------------------------|--------------|--|----------------------|------------------------|
| 霸 / Cadmium (Cd) | mg/kg | 參考IEC 62321-5: 2013方法,以感應耦合 電漿原子發射光譜儀檢測./ With reference to IEC 62321-5: 2013 and performed by ICP-AES. | 2 | n.d. |
| 鉛 / Lead (Pb) | mg/kg | 參考IEC 62321-5: 2013方法,以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5: 2013 and performed by ICP-AES. | 2 | n.d. |
| 汞 / Mercury (Hg) | mg/kg | 参考IEC 62321-4: 2013方法,以感應耦合 電漿原子發射光譜儀檢測./ With reference to IEC 62321-4: 2013 and performed by ICP-AES. | 2 | n.d. |
| 六價络 / Hexavalent Chromium Cr(VI) | mg/kg | 参考IEC 62321: 2008方法,以UV-VIS檢測. / With reference to IEC 62321: 2008 and performed by UV-VIS. | 2 | n.d. |
| 銻 / Antimony (Sb) | mg/kg | 参考US EPA 3052方法,以感應耦合電漿原 子發射光譜儀檢測. / With reference to US EPA Method 3052. Analysis was performed by ICP-AES. | 2 | n.d. |

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| 測試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限値 (MDL) | 結果 (Result) No.1 |
|---|--------------|--|----------------------|------------------------|
| 鄰苯二甲酸甲苯基丁酯 / BBP (Benzyl butyl phthalate) (CAS No.: 85-68-7) | % | 参考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.003 | n.d. |
| 鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7) | % | 参考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.003 | n.d. |
| 鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761-40-0; 68515-49-1) | % | 参考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.01 | n.d. |
| 鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553-12-0; 68515-48-0) | % | 参考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.01 | n.d. |
| 鄰苯二甲酸二正辛酯 / DNOP (Di-n- octyl phthalate) (CAS No.: 117- 34-0) | % | 参考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.003 | n.d. |
| 鄰苯二甲酸二丁酯 / DBP (Dibutyl Dhthalate) (CAS No.: 84-74-2) | % | 参考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.003 | n.d. |
| 郝苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84- i9-5) | % | 參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS. | 0.003 | n.d. |

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|---|--------------|---|----------------------|------------------------|
| 六溴環十二烷及所有主要被辨别出的 異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α- HBCDD, β- HBCDD, γ- HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8)) | mg/kg | 參考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 method. Analysis was performed by GC/MS. | 5 | n.d. |
| 多溴聯苯總和 / Sum of PBBs | mg/kg | 參考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 and performed by GC/MS. | _ | n.d. |
| 一溴聯苯 / Monobromobiphenyl | mg/kg | | 5 | n.d. |
| 二溴聯苯 / Dibromobiphenyl | mg/kg | | 5 | n.d. |
| 三溴聯苯 / Tribromobiphenyl | mg/kg | | 5 | n.d. |
| 四溴聯苯 / Tetrabromobiphenyl | mg/kg | | 5 | n.d. |
| 五溴聯苯 / Pentabromobiphenyl | mg/kg | | 5 | n.d. |
| 六溴聯苯 / Hexabromobiphenyl | | | 5 | n.d. |
| 七溴聯苯 / Heptabromobiphenyl | mg/kg | | 5 | n.d. |
| 八溴哪苯 / Octabromobiphenyl | mg/kg | | 5 | n.d. |
| 九溴聯苯 / Nonabromobiphenyl | mg/kg | | 5 | n.d. |
| 十溴聯苯 / Decabromobiphenyl | mg/kg | | 5 | n.d. |

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Test Report

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| 測試項目 (Test Items) | 單位 (Unit) | 測試方法 (Method) | 方法偵測 極限値 (MDL) | 結果 (Result) No.1 |
|---|--------------|---|----------------------|------------------------|
| 多溴聯苯醚總和 / Sum of PBDEs | mg/kg | 参考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 and performed by GC/MS. | - | n.d. |
| 一溴聯苯醚 / Monobromodiphenyl ether | mg/kg | | 5 | n.d. |
| 二溴聯苯醚 / Dibromodiphenyl ether | mg/kg | | 5 | n.d. |
| 三溴聯苯醚 / Tribromodiphenyl ether | mg/kg | | 5 | n.d. |
| 四溴聯苯醚 / Tetrabromodiphenyl ether | mg/kg | | 5 | n.d. |
| 五溴聯苯醚 / Pentabromodiphenyl ether | mg/kg | | 5 | n.d. |
| 六溴聯苯醚 / Hexabromodiphenyl ether | mg/kg | | 5 | n.d. |
| 七溴聯苯醚 / Heptabromodiphenyl ether | mg/kg | | 5 | n.d. |
| へ溴聯苯醚 / Octabromodiphenyl ether | mg/kg | | 5 | n.d. |
| 九溴聯苯醚 / Nonabromodiphenyl ether | mg/kg | | 5 | n.d. |
| 十溴聯苯醚 / Decabromodiphenyl ether | mg/kg | | 5 | n.d. |
| 鹵素 / Halogen | | | | 11 + 14 + |
| 鹵素(氯)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8) | mg/kg | 參考BS EN 14582:2007,以離子層析儀分析./ With reference to BS EN 14582:2007. Analysis was performed by IC. | 50 | n.d. |
| 鹵素(氣)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1) | | | 50 | n.d. |
| 鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2) | mg/kg | | 50 | n.d. |
| 商素(碘)/ Halogen-Iodine (I) (CAS No.: 14362-44-8) | mg/kg | | 50 | n.d. |

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33, Wu Chuan Rd., New Taipei Industrial Park, New Taipei City, Taiwan / 新北市新北產業園區五檔路33號 t+886 (02)2299 3279 1+886 (02)2299 3237 www.sgs.tw



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備註(Note):

- 1. mg/kg = ppm : 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未检出)
- 3. MDL = Method Detection Limit (方法偵測極限値)
- 4. "-" = Not Regulated (無規格値)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個别單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

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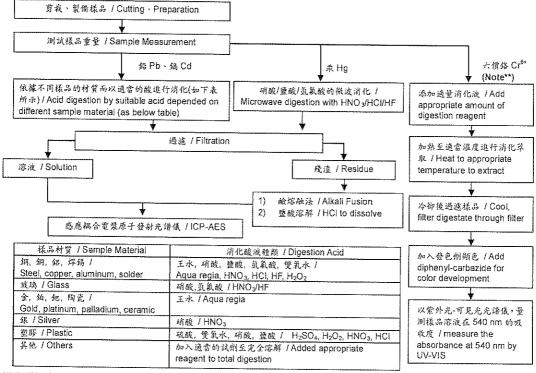
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- 1) 根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外) / These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁵⁺ test method excluded)
- 渊試人員:楊登偉 / Name of the person who made measurement: Climbgreat Yang
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



Note** (For IEC 62321)

(1) 針對非金屬材料加入鹼性消化液,加熱至 90~95℃萃取. / For non-metallic material, add alkaline digestion reagent and heat to 90~95℃ (2) 針對金屬材料加入純水,加熱至沸腾萃取. / For metallic material, add pure water and heat to boiling.

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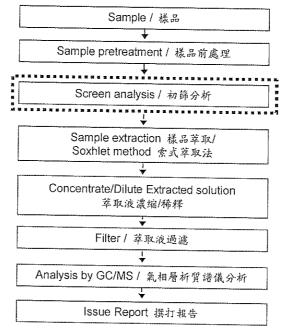
多溴聯苯/多溴聯苯醚分析流程圖 / PBB/PBDE analytical FLOW CHART

- 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang

初次測試程序 / First testing process ———

選擇性篩檢程序 / Optional screen process ••••••

確認程序 / Confirmation process - ⋅ - ⋅ ▶



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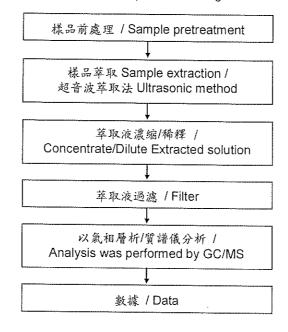
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六溴環十二烷分析流程圖 / HBCDD analytical flow chart

- 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



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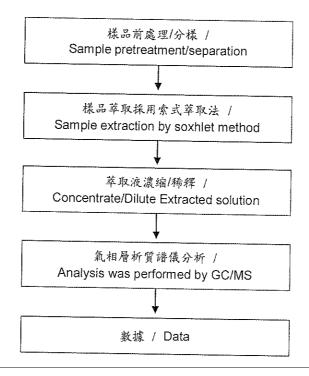
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可塑劑分析流程圖 / Analytical flow chart of phthalate content

■ 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong

■ 測試負責人:張啓與 / Name of the person in charge of measurement: Troy Chang



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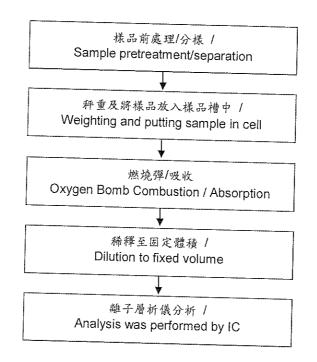
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鹵素分析流程圖 / Analytical flow chart of halogen content

- 測試人員:陳恩臻 / Name of the person who made measurement: Rita Chen
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



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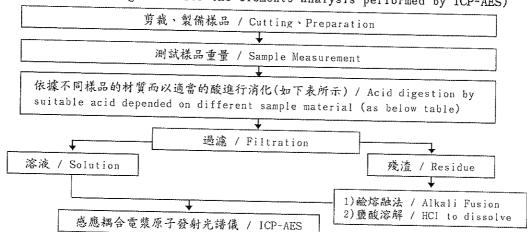
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- 1) 根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.
- 2) 測試人員:楊登偉 / Name of the person who made measurement: Climbgreat Yang
- 3) 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang

元素以 ICP-AES 分析的消化流程圖

(Flow Chart of digestion for the elements analysis performed by ICP-AES)



| | " |
|---|---------------------------------------|
| 鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder | 王水,硝酸,鹽酸,氫氟酸,雙氧水 / |
| | Aqua regia, HNO3, HCl, HF, H2O2 |
| 玻璃 / Glass | 硝酸 葡萄酸 / HNO /HE |
| 金,铂,鲃,陶瓷 / Gold, platinum, palladium, ceramic | 王水 / Aqua regia |
| 銀 / Silver | 硝酸 / HNO: |
| 塑膠 / Plastic | 硫酸.雙氧水,硝酸,鹽酸 / HaSOt, HaOt, HNOs, HC1 |
| 其他 / Others | 加入適當的試劑至完全溶解 / Added appropriate |
| | reagent to total digestion |

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Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(東莞臺慶精密電子有限公司 / TAI-TECH ADVANCED ELECTRONICS (DONGGUAN) CO. LTD.)

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(耀鑚科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

桃園縣楊梅市幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI CITY, TAO-YUAN HSIEN. TAIWAN R. O. C.

(廣東省東莞市黄江鎮黃牛埔福祥街2號 / NO. 2, FUXIANG STREET, HUANGNIUPU, HUANGJIANG TOWN, DONGGUAN, GUANGDONG)

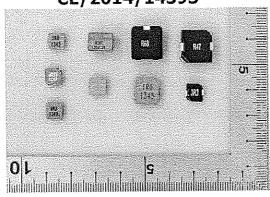
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(桃園縣中壢市中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN (R. O. C.))

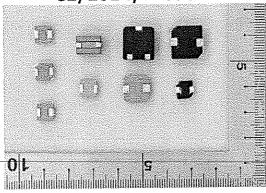
* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2014/14393



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** 報告結尾 (End of Report) **

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